

IN THE CLAIMS:

1. (Previously Presented) A display device comprising:

an active matrix substrate having a peripheral portion and a driver circuit section comprising a plurality of circuit elements and a plurality of polycrystalline silicon thin film transistors;

a counter substrate;

a liquid crystal material filled between the active matrix substrate and the counter substrate; and

an individually-wired line array for supplying a clock signal, a data signal or electric power to the plurality of circuit elements in the driver circuit section, wherein the individually-wired line array is extended to the peripheral portion of the active matrix substrate, wherein:

the peripheral portion of the active matrix substrate comprises a multi-layer bus line-equipped section having a bus line located on the insulator, the bus line is connected to the individually-wired line array via the via hole, and the bus line comprises a connecting terminal for connecting the display device to an external circuit; and

the insulator is a pre-formed resin substrate having a bus line located on a surface thereof and a via hole in the substrate.

2. (Cancelled)

3. (Previously Presented) The display device according to claim 1, wherein the resin substrate comprising an aramid-epoxy resin.

4. (Previously Presented) The display device according to claim 1, wherein the via hole is filled with electrically conductive paste.

5. (Previously Presented) The display device according to claim 1, wherein the resin substrate is a multi-layer structure comprising a plurality of layers in which said bus line is located on a surface of an inner layer thereof as well as on a surface of the outermost layer thereof, and the bus lines are

selectively connected to each other via a via hole in each of the layers to form a three-dimensional wiring structure.

6. (Previously Presented) The display device according to claim 4, wherein the electrically conductive paste partially protrudes from a lower opening of the via hole, and the active matrix substrate and the resin substrate are bonded together with the protruding portion of the electrically conductive paste.

7. (Previously Presented) The display device according to claim 5, wherein an electrically conductive paste fills the via hole; the electrically conductive paste protrudes from a lower opening of the via hole; and the electrically conductive paste partially protrudes from the opening of the via hole, and the active matrix substrate and the resin substrate are bonded together with the protruding portion of the electrically conductive paste.

8. (Previously Presented) The display device according to claim 1, wherein the resin substrate and the active matrix substrate are bonded with an adhesive comprising a material having a thermoplastic property.

9. (Previously Presented) The display device according to claim 1, wherein the resin substrate and the active matrix substrate are bonded with an adhesive comprising an anisotropic conductive resin or a silver paste.

10. (Previously Presented) The display device according to claim 1, wherein the resin substrate is a film substrate, and is detachably bonded to the active matrix substrate.

11. (Previously Presented) The display device according to claim 10, wherein the film substrate is made of a resin comprising polyimide or epoxy.

12. (Previously Presented) The display device according to claim 1, further comprising a semiconductor chip of an external

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circuit, said semiconductor chip being mounted on the resin substrate and is connected to the bus line.

13. (Previously Presented) The display device according to claim 12, wherein the semiconductor chip is buried in the via hole.

14. (Previously Presented) The display device according to claim 1, wherein the bus line in the multi-layer bus line-equipped section is a thick film.

15. (Previously Presented) The display device according to claim 14, wherein the insulator in the multi-layer bus line-equipped section is a thick film.

16. (Previously Presented) A display device comprising:
an active matrix substrate having a peripheral portion and a driver circuit section comprising a plurality of circuit elements and a plurality of polycrystalline silicon thin film transistors;

a counter substrate;

a liquid crystal material filled between the active matrix substrate and the counter substrate; and

an individually-wired line array for supplying a clock signal, a data signal or electric power to the plurality of circuit elements in the driver circuit section, wherein the individually-wired line array is extended to the peripheral portion of the active matrix substrate, wherein:

the active matrix substrate has a recessed groove located in the peripheral portion;

a bus line connected to the individually-wired line array is buried in the groove, the bus line is a layered structure comprising a copper foil layer, a copper plating layer, and a gold-nickel plating layer.

17. (Currently Amended) A display device comprising:

an active matrix substrate having a peripheral portion and a driver circuit section comprising a plurality of circuit elements and a plurality of polycrystalline silicon thin film transistors;

a counter substrate;

a liquid crystal material filled between the active matrix substrate and the counter substrate; and

an individually-wired line array for supplying a clock signal, a data signal or electric power to the plurality of circuit elements in the driver circuit section, wherein the individually-wired line array is extended to the peripheral portion of the active matrix substrate, wherein:

the active matrix substrate ~~has~~ comprises an organic resin layer in the peripheral portion thereof, a connecting electrode, and a bus line connected to the individually-wired line array ~~is~~ and buried in the organic resin layer;

the organic resin comprises a photosensitive resin;

the organic resin layer has a via hole formed by photolithography; and

the bus line is electrically connected to the individually wired line array via a ~~the~~ connecting electrode filled located in the via hole.

18. (Cancelled)

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19. (Previously Presented) The display device according to claim 17, wherein the bus line is an electrically conductive thermosetting resin.

20. (Previously Presented) The display device according to claim 16, wherein the bus line is a pre-formed metal fine wire.

21. (Previously Presented) The display device according to claim 17, wherein the bus line is a pre-formed metal fine wire.

22. (Cancelled)

23. (Previously Presented) The display device according to claim 17, wherein the bus line is produced by plating.

24. (Cancelled)

25. (Previously Presented) The display device according to claim 23, wherein the bus line is a layered structure comprising

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a copper foil layer, a copper plating layer, and a gold-nickel plating layer.

26. (Previously Presented) The display device according to claim 16, wherein the bus line is formed by depositing in which a thin, electrically conductive layer is formed in advance and a plurality of different metal layers are selectively deposited on the electrically conductive layer.

27. (Previously Presented) The display device according to claim 17, wherein the bus line is formed by depositing in which a thin, electrically conductive layer is formed in advance and a plurality of different metal layers are selectively deposited on the electrically conductive layer.

28. (Previously Presented) The display device according to claim 1, wherein, in place of the liquid crystal, a rare gas is located between the substrates, the rare gas for forming a plasma discharge to perform a display operation.

29.-38. (Cancelled)